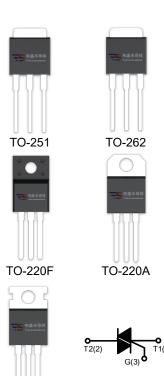


#### **DESCRIPTION:**

With high ability to withstand the shock loading of large current, BTA208X-600F series triacs provide high dv/dt rate with strong resistance to electromagnetic interface. With high commutation performances, 3 quadrants products especially recommended for use on inductive load.



TO-220C

#### **MAIN FEATURES**

Symbol	Value	Unit
I <sub>T(RMS)</sub>	8	Α
VDRM /VRRM	600/800/1200	V

#### **ABSOLUTE MAXIMUM RATINGS**

Parameter		Symbol	Value	Unit
Storage junction temperature range		T <sub>stg</sub>	-40 - 150	$^{\circ}\mathbb{C}$
Operating junction temperature range		Tj	-40 - 125	$^{\circ}\!\mathbb{C}$
Repetitive peak	off-state voltage (Tj=25℃)	$V_{DRM}$	600/800/1200	V
Repetitive peak r	reverse voltage (Tj=25℃)	V <sub>RRM</sub>	600/800/1200	V
Non repetitive surge peak Off-state voltage		V <sub>DSM</sub>	V <sub>DRM</sub> +100	V
Non repetitive peak reverse voltage		V <sub>RSM</sub>	V <sub>RRM</sub> +100	V
RMS on-state current	TO-251/TO-220C TO-220A(Non-Ins) (Tc=100°C) TO-220A(Ins)/ TO-220F(Ins) (Tc=95°C) TO-262 (Tc=90°C)	It(RMS)	8	А
Non repetitive surge peak on-state current (full cycle, F=50Hz)		I <sub>TSM</sub>	80	А

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I <sup>2</sup> t value for fusing (tp=10ms)	l <sup>2</sup> t	32	$A^2s$
Critical rate of rise of on-state current $(I_G=2\times I_{GT})$	dl/dt	50	A/µs
Peak gate current	I <sub>GM</sub>	4	Α
Average gate power dissipation	P <sub>G(AV)</sub>	1	W
Peak gate power	P <sub>GM</sub>	5	W

# **ELECTRICAL CHARACTERISTICS** ( $T_j$ =25 $^{\circ}$ C unless otherwise specified)

### 3 Quadrants

Symbol	Test Condition Q	Quadrant	Value				Unit	
				TW	SW	CW	BW	Offic
lgт	V <sub>D</sub> =12V R <sub>L</sub> =33Ω	I - II -III	MAX	5	10	35	50	mA
V <sub>GT</sub>		I - II -III	MAX	1.5			٧	
$V_{GD}$	V <sub>D</sub> =V <sub>DRM</sub> T <sub>j</sub> =125℃ R <sub>L</sub> =3.3KΩ	I - II -III	MIN	0.2			V	
IL	I <sub>G</sub> =1.2I <sub>GT</sub>	I -III	MAX	20	25	50	70	mΛ
		II	IVIAA	25	35	70	90	mA
lн	I <sub>TM</sub> =100mA		MAX	15	20	40	60	mA
dV/dt	V <sub>D</sub> =2/3V <sub>DRM</sub> Gate Open T <sub>j</sub> =125℃		MIN	50	200	500	1000	V/µs

## 4 Quadrants

Symbol	Test Condition	Quadrant		Va	Unit	
	rest Condition			С	В	Offic
lar		I - II -III	MAX	25	50	mA
lgт	V <sub>D</sub> =12V R <sub>L</sub> =33Ω	IV		50	50 70	
V <sub>G</sub> T		ALL	MAX	1.	V	
V <sub>GD</sub>	$V_D=V_{DRM}$ $T_j=125$ °C $R_L=3.3$ $KΩ$	ALL	MIN	0	V	
IL	I <sub>G</sub> =1.2I <sub>GT</sub>	I -III-IV	MAX	50	70	mA
		II		70	90	IIIA
lμ	I <sub>TM</sub> =200mA		MAX	40	60	mA
dV/dt	V <sub>D</sub> =2/3V <sub>DRM</sub> Gate Open T <sub>j</sub> =125℃		MIN	200	500	V/µs

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### **STATIC CHARACTERISTICS**

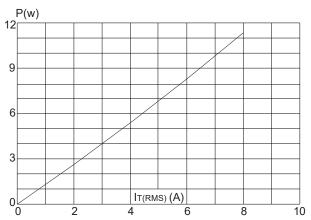
Symbol	Parameter		Value(MAX)	Unit
V <sub>TM</sub>	I <sub>тм</sub> =11A tp=380µs	T <sub>j</sub> =25℃	1.5	V
IDRM	V <sub>D</sub> =V <sub>DRM</sub> V <sub>R</sub> =V <sub>RRM</sub>	Tj=25℃	5	μΑ
I <sub>RRM</sub>		T <sub>j</sub> =125℃	1	mA

### **THERMAL RESISTANCES**

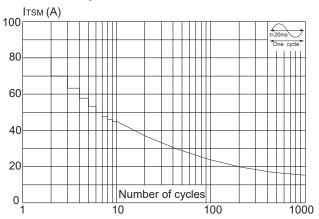
Symbol	Parameter		Value	Unit
R <sub>th(j-c)</sub>	junction to case(AC)	TO-251	2.1	°C/W
		TO-220A(Ins)	2.7	
		TO-220C/ TO-220A(Non-Ins)	1.8	
		TO-220F(Ins)	2.9	
		TO-262	3.0	

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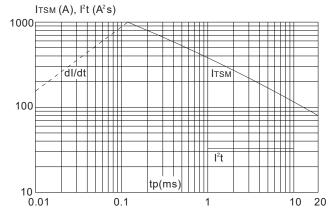
**FIG.1:** Maximum power dissipation versus RMS on-state current



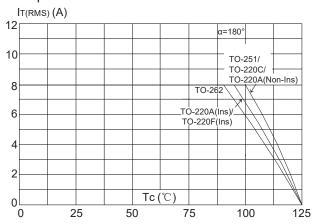
**FIG.3:** Surge peak on-state current versus number of cycles



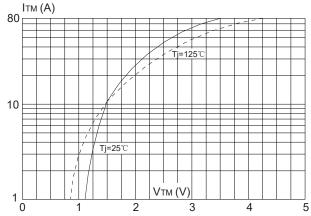
**FIG.5:** Non-repetitive surge peak on-state current for a sinusoidal pulse with width tp<20ms, and corresponging value of I<sup>2</sup>t (dI/dt < 50A/µs)



**FIG.2:** RMS on-state current versus case temperature



**FIG.4:** On-state characteristics (maximum values)



**FIG.6:** Relative variations of gate trigger current, holding current and latching current versus junction temperature

